

PCN-2014-543

Assembly Site Transfer from StatsChipPac Kuala Lumpur, Malaysia (SCM) to ANST Wuxi CHINA for the CS4265-CNZ(R) component

Process/Product Change Notification (Reference Advance PCN-2014-523)

Date: June 2014

Dear Customer:

This is a Final Announcement of the Assembly Site Transfer from StatsChipPac Kuala Lumpur, Malaysia to ANST Wuxi CHINA for the CS4265–CNZ(R) component that is currently offered by Cirrus Logic. This Final announcement is a follow on to the Advance PCN notification communicated to all customers in February of this calendar year 2014. The details of this Assembly Site Transfer are outlined on the following pages.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the lifetime buy offering/discontinuance plan.

The described change(s) within this PCN will not be realized or take effect any earlier than **60** days from the date of this notification, unless a customer agreement has been reached on an earlier implementation of the change or successful completion of the defined qualification has been realized.

Please note that the notification period has been reduced from 90 days to 60 days as the SCM site recently informed Cirrus that the closure date has been moved forward from December 31^{st} , 2014 to September 30^{th} , 2014. Cirrus has no control over any changes to the site closure date.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Cirrus Logic would like to take this opportunity to thank our customers for their cooperation and assistance in this respective matter. Any specific or immediate inquiries should be directed to your local Field Sales Representative.

Sincerely,

PCN Coordinator Cirrus Logic Corporate Quality Phone: +1(512) 851-4000

Attachment: 1

Products Affected:

Cirrus Logic

The devices listed on this page are the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

Technical details of this Process / Product Change follow on the next page(s).

PCN Number:				2014-543			PC	PCN Date:			June 2014	
Title:		Assembly Site Transfer from StatsChipPac Kuala Lumpur, Malaysia to ANST Wuxi								NST Wuxi		
	CHINA for the CS4265-CNZ(R) component											
Customer Local Fi			ield Sales			Phone:	(512)		Dept:	Corporate		
			entative				851-4000			Quality		
Кергез			Citative									
Proposed 1 st Ship Date				: August 2014			Estimated Sample					June 2014
)	Availability date:						
Change Type:				A	Assembly Site Transfer to an existing Qualified Cirrus Logic Site							
			Lo	ocation: Change Type = Major								
Assembly Site					Assembly Process			\boxtimes	Assembly Materials			
	Design				Electrical Specification				Mechanical Specification			
	☐ Test Site ☐			Packing/Shipping/Labeling				Test P	rocess			
	☐ Wafer Bump ☐]	Wafer Bump Material				Wafer Bump Process				
	Site											
	Waf	er Fal	b Site			Wafer Fab Mate	rials			Wafer	Fab Pr	ocess

PCN Details						
Description of Change:						
Cirrus Logic's package Assembly and Test Supplier, StatsChipPac, has announced their site in Kuala Lumpur, Malaysia will close by September 30th, 2014.						
Cirrus Logic is qualifying and will move these products to the existing qualified subcontractor (ANST) site location in Wuxi CHINA.						
Below you will find an outline of the described changes for these components:						
 CS4265-CNZ(R) Assembly Site Change: From: StatsChipPac Kuala Lumpur, M PackMark COO Symbolization: From: MYS Mold Compound: From: Symitoms EME C770 	→	To: CHN				
From: Sumitomo EME-G770 • Wire Diameter From: 1.0 mil	→	To: Hitachi CEL-9240HF To: 0.8 mil (Industry Standard)				
Reason for Change:						

Kuala Lumpur, Malaysia will close by September 30th, 2014.

PCN-2014-543

Cirrus Logic's package Assembly and Test Supplier, StatsChipPac, has announced their site in

Cirrus Logic is qualifying and will move these products to the existing qualified subcontractor (ANST) site location in Wuxi CHINA.

Special Note:

As a full services supplier and in order to ensure continuity of supply as well as sustain quality an accelerated timeframe has been established for the full transfer of said product no later than September 30th, 2014.

Earlier production level material may be available from the qualified subcontractor (ANST) site location in Wuxi CHINA, but shipment(s) from Cirrus Logic are contingent on successful completion of the designated site transfer qualification.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

Anticipated No Adverse Impact to the Quality & Reliability of said product; as Transfer Site is an existing Cirrus Logic qualified subcontractor (ANST) site (Wuxi CHINA) and considered low risk.

Product Affected: | Table I

Customer Material Part Number Cirrus Logic Part Number

Device 1: CS4265-CNZ(R)

Changes to product identification resulting from this PCN:

The Cirrus Logic component symbolization on the external face of the device reflects the designated Assembly Site Country Of Origin.

Below you will find a representative example:

Our part: **CS4265-CNZ(R)**

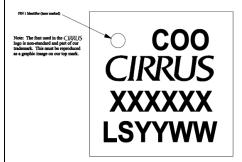
Mark format: **234** Mark change:

Assembly vendor = None (not shown on mark)
 COO = changing From: MYS → TO: CHN

Line 1: Country Of Origin (COO)

Line 2: Logo Line

Line 3: Part Number (6 spaces max.) Line 4: Package Mark (6 spaces max.)



With the Assembly Site Transfer to ANST Wuxi CHINA, the material will receive the appropriate designation for the Assembly Site Country Of Origin.

Qualification Data:

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications. **Qualification Schedule:** Start: March 2014 End: July 2014 **Qualification Device Construction Details:** Device 1 Device 2 Part Number(s): CS4265-CNZ(R) Wafer Fab Site: ΥF Wafer Technology: 0.35 Die Size: 9.85 mm ANST Wuxi CHINA **Assembly Site:** 32QFN5Z 5x5 Package Type/Code: **Moisture Level:** MSL (Moisture Sensitivity Level) 3 **Package Pins:** 32 NL QFN **Lead Frame Material:** Cu (Copper) **Mold Compound** CEL-9240HF Supplier: Hitachi **Lead Finish:** Matte Sn Plate Ablebond 8290 **Die Attach Material** Wire Diameter: 0.8mil

Au (Gold)

Wire Base Metal:

The Qualification Plans are designed using JEDEC and other applicable industry standards. An overall summary of the Qualification results will be submitted upon completion.

CS4265-CNZ(R) Qualification

CS4265-CNZ(R) Qualification:							
Reliability Test			Sample Size (PASS/FAIL)				
Pre-Conditioning	JEDEC J-STD-020A	MSL3 / 260°C (1 Lot)	231 / 0				
THB (Temperature Humidity Bias)	JESD22 A101	85C/85%RH/1000 Hrs (THB) (1 Lot)	77 / 0				
Auto Clave	JESD22 A102	121°C/100%RH/15 psig for 96 Hrs (AC) (1 Lot)	77 / 0				
Temperature Cycle	JESD22 A104	-65°C to +150°C for 500 cycles (1 Lots)	77 / 0				
WBS (Wire Bond Shear)	JESD22 B116	Paragraph 4 (Procedure) (1 Lot)	5 units / lot				
WBP (Wire Bond Pull)	MIL-STD-883 Method 2011	Paragraph 3 (Procedure) (1 Lot)	5 units / lot				
SD (Solderability)	JESD22 B102	93°C / 8 Hr steam age before SD (1 Lot)	15 units / lot				
PD (Physical Dimensions)	JESD22 B100 + B108	Package outline per JESD95 Cpk > 1.50 per JESD95 (1 Lot)	20 / 0				
ED (Electrical Distribution)	JESD86	Parametric limits per datasheet or user spec Designed for -40°C to +105°CC	30 / 0				
HTSL (High Temperature Storage Life)	JESD22 A103	150°C for 1000 Hrs (1 Lot)	45 / 0				

Notes:

• Qualification tests "pass" on zero fails for each test